WHAT IS CLAIMED IS:

1. An integrated circuit, comprising:

a conductive layer;

a first die adhered to the conductive layer;

a first adhesive layer on a top surface of the first die;

a plurality of spacers adhered to the first adhesive layer, the plurality of spacers arranged in a rectangular pattern on top of the first die;

a second die having a second adhesive layer on a bottom surface of the second die, wherein the second adhesive layer is adhered to the plurality of spacers such that the plurality of spacers are between the first and second dies;

a plurality of wires coupled to the conductive layer and to the first and second dies operable to conduct electricity between the conductive layer and the first and second dies; and

an encapsulating material operable to form the first and second dies, the spacers, the conductive layer, and the wires into a single package.

2. An integrated circuit, comprising:

a first die;

a second die;

a plurality of spacers between the first die and the second die, wherein each of the spacers is attached to the first die and the second die.

3. The integrated circuit of Claim 2, wherein the spacers are adhered to the dies.

4. The integrated circuit of Claim 2, wherein the spacers are formed from silicon.

5. The integrated circuit of Claim 2, wherein the spacers are formed from an adhesive material.

6. The integrated circuit of Claim 2, wherein:

there are exactly four spacers in the plurality of spacers; and

the spacers are arranged in a rectangular pattern.

7. The integrated circuit of Claim 2, wherein:

the dies are formed from a first material; and

the spacers are formed from a second material different from the first material.

8. The integrated circuit of Claim 2, wherein the spacers are integral to the first die.

9. A method of forming an integrated circuit, comprising:

placing a first die;

adhering a plurality of spacers to the first die;

adhering a second die to the plurality of spacers such that the spacers are between the first and second dies.

10. The method of Claim 9, wherein:

the plurality of spacers are a first plurality of spacers, and the first plurality of spacers is adhered to a first side of the second die; and

the method further comprises:

adhering a second plurality of spacers on a second side of the second die; and

adhering a third die to the second plurality of spacers such that the second plurality of spacers is in between the second and third dies.

11. The method of Claim 9, further comprising enclosing the first and second dies and the spacers in an encapsulating material.

12. The method of Claim 9, wherein:

the step of placing the first die comprises adhering the first die to a conductive layer; and

the method further comprises:

coupling a plurality of wires to the conductive layer; and

coupling each of the wires to at least one of the dies.

13. The method of Claim 9, wherein:

there are exactly four spacers in the plurality of spacers; and

the step of adhering the spacers comprises arranging the spacers in a rectangular arrangement.

14. The method of Claim 9, wherein:

the dies are formed from a first material; and

the spacers are formed from a second material different from the first material.

15. An integrated circuit made by a process, the process comprising:

placing a first die;

adhering a plurality of spacers to the first die;

adhering a second die to the plurality of spacers such that the spacers are between the first and second dies.

16. The integrated circuit of Claim 15, wherein:

the plurality of spacers are a first plurality of spacers, and the first plurality of spacers is adhered to a first side of the second die; and

the process further comprises:

adhering a second plurality of spacers on a second side of the second die; and

adhering a third die to the second plurality of spacers such that the second plurality of spacers is in between the second and third dies.

17. The integrated circuit of Claim 15, wherein the process further comprises enclosing the first and second dies and the spacers in an encapsulating material.

18. The integrated circuit of Claim 15, wherein:

the step of placing the first die comprises adhering the first die to a conductive layer; and

the process further comprises:

coupling a plurality of wires to the conductive layer; and

coupling each of the wires to at least one of the dies.

19. The integrated circuit of Claim 15, wherein:

there are exactly four spacers in the plurality of spacers; and

the step of adhering the spacers comprises arranging the spacers in a rectangular arrangement.

20. The integrated circuit of Claim 15, wherein:

the dies are formed from a first material; and

the spacers are formed from a second material different from the first material.